Atty. Dkt. No.: 2557-000206/US

DECLARATION

As a below named inventor, I hereby declare that:

the specification of which (check one)

My residence, mailing address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

INTEGRATED MONITORING BURN-IN TEST METHOD FOR MULTI-CHIP PACKAGE

•		
		is attached hereto. or was filed on as Application Serial No. or PCT International Application No (if applicable).
I hereby s specificat	state that tion, inclu	I have reviewed and understand the contents of the above identified ding the claims, as amended by any amendment referred to above.
defined i	n 37 CFF	e duty to disclose information which is material to patentability as R § 1.56, including for continuation-in-part applications, material became available between the filing date of the prior application and

I hereby claim foreign priority benefits under 35 U.S.C. §§ 119(a)-(d) or 365(b) of any foreign application(s) for patent or inventor's certificate, or 365(a) of any PCT international application which designated at least one country other than the United States of America, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or any PCT international application having a filing date before that of the application on which priority is claimed:

the national or PCT international filing date of the continuation-in-part application.

	PRIOR FOREIGN AP	PLICATION(S)		n
APPN. SERIAL NO.	COUNTRY	DATE FILED PRIORITY		Y CLAIM
	_	(MM/DD/YYYY)	Yes	No
2003-3648	Korea	1/20/2003		

I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) listed below:

PRIOR PROVISIONAL APPLICATION(S)			
DATE FILED (MM/DD/YYYY)			

I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s) listed below:

	PRIOR U.S. APPLICATION(S)	:
APPN. SERIAL NO.	DATE FILED (MM/DD/YYYY)	STATUS - PATENTED, PENDING, ABANDONED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

POWER OF ATTORNEY

I hereby appoint the following attorneys with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

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